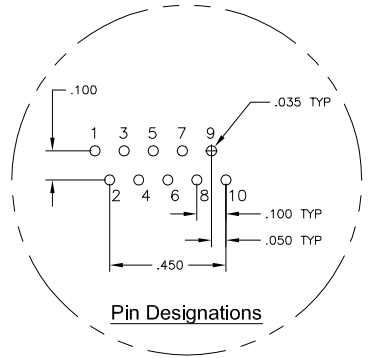
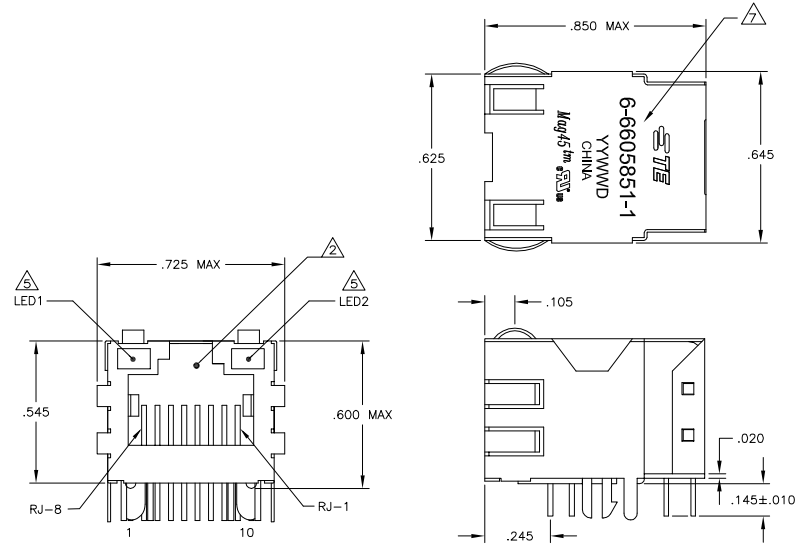
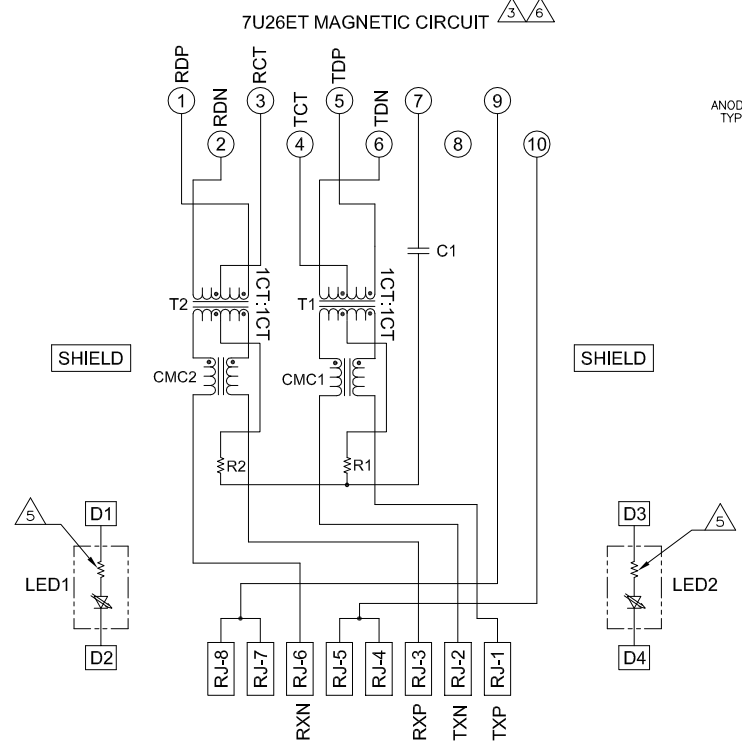


LOC	DATE	REVISIONS
AA	22	
B1	REVISED PER ECO-11-005140	13APR11 RK HMR
C	ECO-11-013919	30MAY2011 EL LR

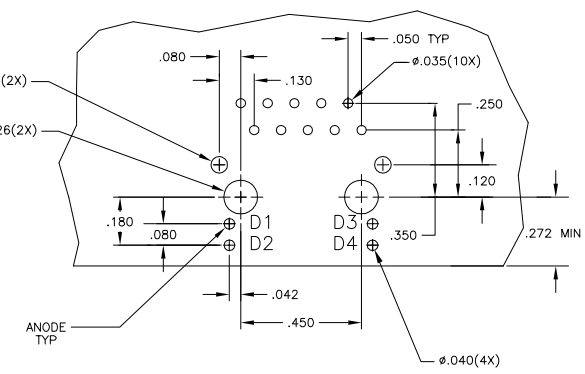
MECHANICAL:



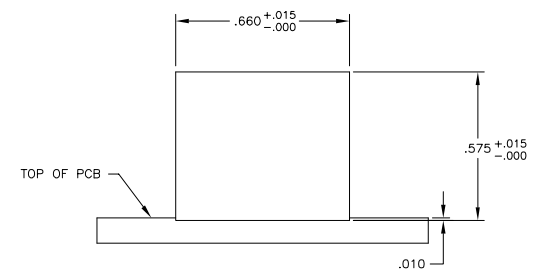
ELECTRICAL:



C1 = 1000 pF, 2kV DECOUPLING CAPACITOR
R1-R2 = 75 OHMS, 1/16W, 5% RESISTORS



Suggested PCB Layout
(Component Side)



Suggested Panel Cutout

- MATERIALS:**
- HOUSING - THERMOPLASTIC PET POLYESTER FLAMMABILITY RATING UL 94V-0.
 - SHIELD - .010" THICK, C26800 BRASS PREPLATED WITH 30μINCH MIN SEMI-BRIGHT NICKEL. SOLDER TABS POST DIPPED WITH 100μINCH MIN SAC SOLDER.
 - MOD JACK CONTACTS - 0.0157" x 0.018" PHOSPHOR BRONZE, 50μINCH MIN OVERALL NICKEL UNDERPLATE, WITH SELECT 50μINCH MIN HARD GOLD FINISH PLATE. SOLDER TAILS WITH 100μINCH MIN MATTE TIN AND/OR SAC SOLDER DIP.
 - LIGHT EMITTING DIODE(LED) - DIFFUSED EPOXY LENS, .020" x .020" CARBON STEEL WIREFRAME LEADS PRE-PLATED WITH 80μINCH SILVER OVER 40μINCH NICKEL UNDERPLATE OVER 40μINCH COPPER UNDERPLATE, POST-PLATED WITH 100μINCH MIN MATTE TIN AND/OR SAC SOLDER DIP OR PURE TIN SOLDER DIP.
- RJ45 JACK CAVITY CONFORMS TO FCC RULES AND REGULATIONS PART 68, SUB PART F.**
- MAGNETICS**
- IMPEDANCE: 100 OHMS
 - TURNS RATIO (CHIP-CABLE): TX = 1:1, RX = 1:1
 - OPEN CIRCUIT INDUCTANCE (OCL): 350μH MIN @100kHz, 0.1VRMS, 8mADC BIAS FROM -40°C TO +85°C, TX AND RX
 - POE CURRENT: 350mADC MAX
 - PERFORMANCE @ 25°C:
- INSERTION LOSS (IL):** 1.1dB MAX FROM 0.5MHz TO 100MHz
RETURN LOSS (RL): 18dB MIN FROM 0.5MHz TO 30MHz
 18-20xLOG(f/30)dB MIN FROM 30.1MHz TO 60MHz
 12dB MIN FROM 60.1MHz TO 80MHz
- CROSSTALK ATTENUATION:** 35dB MIN FROM 0.5MHz TO 40MHz
 33-20xLOG(f/50)dB MIN FROM 40.1MHz TO 100MHz
- COMMON MODE REJECTION RATIO (CMRR):** 30dB MIN FROM 0.5MHz TO 100MHz
- ISOLATION VOLTAGE:** 2250VDC (MAX) FOR 60 SECONDS WITH A RISE TIME OF 500V/SEC.
- 4. OPERATING TEMPERATURE:** FROM -40° - +85°C INDUSTRIAL TEMPERATURE RATED.
- LEDS WITH BUILT-IN RESISTOR**
- LEDS ARE DRIVEN WITH 5V VOLTAGE AND THE MAX OPERATING CURRENT IS 20mA.
 LED COLOR - DOMINANT WAVELENGTH (λD): GREEN 568 nm TYP. @ VF=5V
 FORWARD CURRENT (IF): GREEN 12 mA TYP. @ VF=5V
 DOMINANT WAVELENGTH (λD): YELLOW 588 nm TYP. @ VF=5V
 FORWARD CURRENT (IF): YELLOW 13 mA TYP. @ VF=5V
- INDICATED MAGNETIC CONNECTIONS ARE SYMMETRICAL TO SUPPORT AUTO-MDI/MDIX.**
- TE CONNECTIVITY LOGO, PART NUMBER, DATE CODE, COUNTRY OF ORIGIN AND AGENCY APPROVAL MARKING IN APPROXIMATE LOCATION SHOWN.**
- B. THE PART IS RECOMMENDED FOR WAVE SOLDERING PROCESS, PEAK WAVE SOLDERING TEMPERATURE IS 260°C MAX, 10 SECONDS MAX.**

DIMENSIONS:		DRAWING NO.		REV	
INCHES	0.0005	100779	1	1	1
MILLIMETERS	0.0127	100779	1	1	1
MATERIAL:		FINISH:		SCALE:	
STEEL		ZINC PLATE		4:1	
CUSTOMER DRAWING		SCALE		SHEET 1 OF 1	